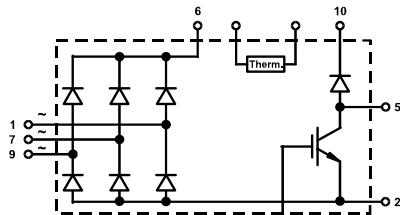
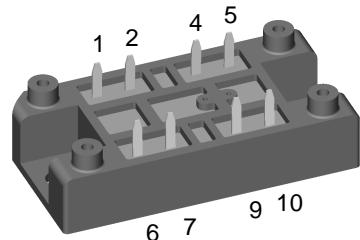


Three Phase Rectifier Bridge with IGBT and Fast Recovery Diode for Braking System

V_{RRM}	Type
V	
1200	VUB 60-12 NO1
1600	VUB 60-16 NO1



$V_{RRM} = 1200-1600 \text{ V}$
 $I_{dAVM} = 70 \text{ A}$



Symbol	Test Conditions	Maximum Ratings		
V_{RRM}		1200 / 1600	V	
I_{dAV}	$T_H = 110^\circ\text{C}$, sinusoidal 120° limited by leads	59	A	
I_{dAVM}		70	A	
I_{FSM}	$T_{VJ} = 45^\circ\text{C}$, $t = 10 \text{ ms}$, $V_R = 0 \text{ V}$	530	A	
	$T_{VJ} = 150^\circ\text{C}$, $t = 10 \text{ ms}$, $V_R = 0 \text{ V}$	475	A	
I^2t	$T_{VJ} = 45^\circ\text{C}$, $t = 10 \text{ ms}$, $V_R = 0 \text{ V}$	1400	A	
	$T_{VJ} = 150^\circ\text{C}$, $t = 10 \text{ ms}$, $V_R = 0 \text{ V}$	1130	A	
P_{tot}	$T_H = 80^\circ\text{C}$ per diode	49	W	
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	1200	V	
V_{GE}	Continuous	± 20	V	
C_{25}	$T_H = 25^\circ\text{C}$, DC	31	A	
C_{70}	$T_H = 70^\circ\text{C}$, DC	23	A	
C_{80}	$T_H = 80^\circ\text{C}$, DC	21	A	
I_{CM}	t_p = Pulse width limited by T_{VJM}	62	A	
P_{tot}	$T_H = 80^\circ\text{C}$	70	W	
V_{RRM}		1200	V	
I_{FAV}	$T_H = 80^\circ\text{C}$, rectangular $d = 0.5$	8	A	
I_{FRMS}	$T_H = 80^\circ\text{C}$, rectangular $d = 0.5$	12	A	
I_{FRM}	$T_H = 80^\circ\text{C}$, $t_p = 10 \mu\text{s}$, $f = 5 \text{ kHz}$	90	A	
I_{FSM}	$T_{VJ} = 45^\circ\text{C}$, $t = 10 \text{ ms}$	75	A	
	$T_{VJ} = 150^\circ\text{C}$, $t = 10 \text{ ms}$	60	A	
P_{tot}	$T_H = 80^\circ\text{C}$	22	W	
T_{VJ}		-40...+150	$^\circ\text{C}$	
T_{VJM}		150	$^\circ\text{C}$	
T_{stg}		-40...+125	$^\circ\text{C}$	
V_{ISOL}	50/60 Hz	3000	V~	
	$I_{ISOL} \leq 1 \text{ mA}$	3600	V~	
M_d	Mounting torque (M5) (10-32 unf)	2-2.5 18-22	Nm lb.in.	
Weight	typ.	35	g	

Data according to IEC 60747

IXYS reserves the right to change limits, test conditions and dimensions.

Features

- Soldering connections for PCB mounting
- Isolation voltage 3600 V~
- Ultrafast freewheel diode
- Convenient package outline
- UL registered E 72873
- Thermistor

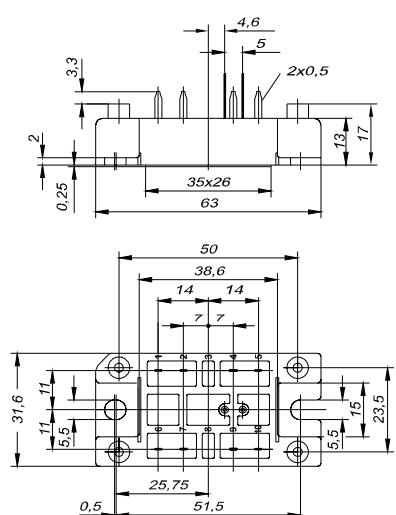
Applications

- Drive Inverters with brake system

Advantages

- 2 functions in one package
- No external isolation
- Easy to mount with two screws
- Suitable for wave soldering
- High temperature and power cycling capability

Dimensions in mm (1 mm = 0.0394")



Symbol	Test Conditions	Characteristic Values		
		$(T_{VJ} = 25^\circ C$, unless otherwise specified)		
		min.	typ.	max.
I_R	$V_R = V_{RRM}$, $T_{VJ} = 25^\circ C$ $V_R = V_{RRM}$, $T_{VJ} = 150^\circ C$		0.1 mA 3 mA	
V_F	$I_F = 25 A$, $T_{VJ} = 25^\circ C$		1.3 V	
V_{TO} r_T	For power-loss calculations only $T_{VJ} = 150^\circ C$		0.85 V 8.5 mΩ	
R_{thJH}	per diode		1.42 K/W	
$V_{BR(CES)}$ $V_{GE(th)}$	$V_{GS} = 0 V$, $I_C = 3 mA$ $I_C = 10 mA$	1200 5	V 7.5 V	
I_{GES}	$V_{GE} = \pm 20 V$		500 nA	
I_{CES}	$T_{VJ} = 25^\circ C$, $V_{CE} = 800 V$ $T_{VJ} = 125^\circ C$, $V_{CE} = 800 V$		250 μA 1 mA	
V_{CEsat}	$V_{GE} = 15 V$, $I_C = 25 A$		3.5 V	
t_{sc} (SCSOA)	$V_{GE} = 15 V$, $V_{CE} = 600 V$, $T_{VJ} = 125^\circ C$, $R_G = 4.7 \Omega$, non repetitive		10 μs	
RBSOA	$V_{GE} = 15 V$, $V_{CE} = 800 V$, $T_{VJ} = 125^\circ C$, $R_G = 4.7 \Omega$, Clamped Inductive load, $L = 100 \mu H$		50 A	
C_{ies}	$V_{CE} = 25 V$, $f = 1 MHz$, $V_{GE} = 0 V$	2.85	nF	
$t_{d(on)}$ $t_{d(off)}$ t_{fi} E_{on} E_{off}	$\left\{ \begin{array}{l} V_{CE} = 600 V, I_C = 25 A \\ V_{GE} = 15 V, R_G = 4.7 \Omega \\ \text{Inductive load; } L = 100 \mu H \\ T_{VJ} = 125^\circ C \end{array} \right.$	100 220 1600 3.5 12	ns ns ns mJ mJ	
R_{thJH}			1 K/W	
I_R	$V_R = V_{RRM}$, $T_{VJ} = 25^\circ C$ $V_R = 800 V$, $T_{VJ} = 150^\circ C$		0.2 mA 6 mA	
V_F	$I_F = 12 A$, $T_{VJ} = 25^\circ C$		2.7 V	
V_{TO} r_T	For power-loss calculations only $T_{VJ} = 150^\circ C$		1.65 V 46 mΩ	
I_{RM}	$I_F = 25 A$, $-di_F/dt = 100 A/\mu s$ $V_R = 100 V$	6.5	7 A	
t_{rr}	$I_F = 1 A$, $-di_F/dt = 100 A/\mu s$ $V_R = 30 V$	50	70 ns	
R_{thJH}			3.12 K/W	
R_{25}	Siemens Typ S 891/2,2k/+9		2.2 kΩ	
d_s d_a	Creep distance on surface Strike distance in air Maximum allowable acceleration		12.7 mm 9.4 mm 50 m/s ²	
Module	NTC			

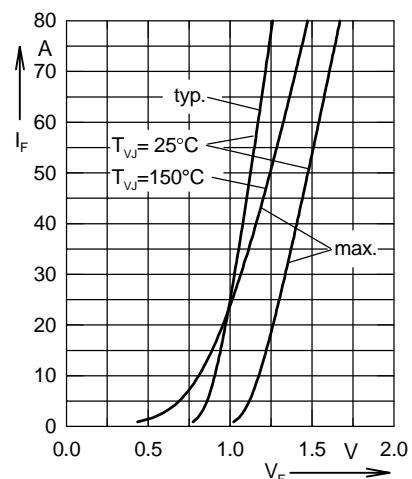


Fig. 1 Forward current versus voltage drop per rectifier diode

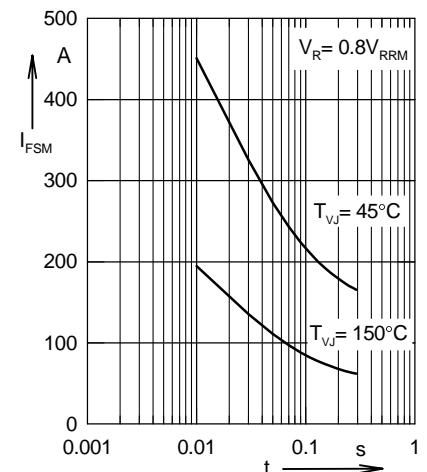


Fig. 2 Surge overload current per rectifier diode

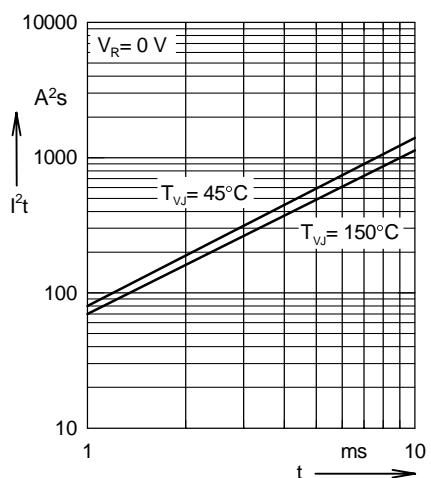


Fig. 3 I^2t versus time per rectifier diode

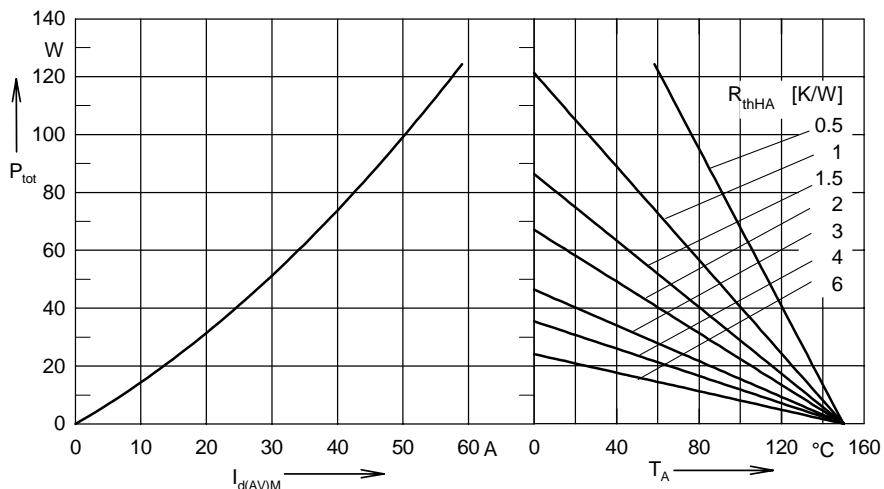


Fig. 4 Power dissipation versus direct output current and ambient temperature (Rectifier bridge)

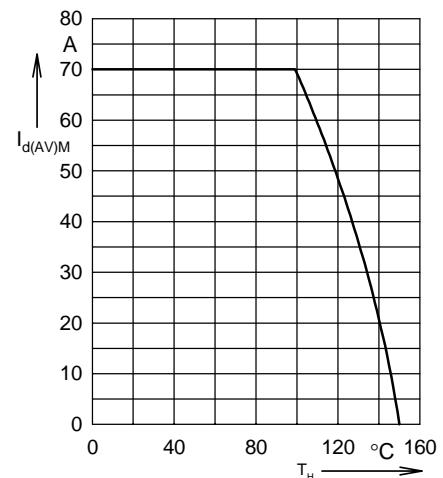


Fig. 5 Maximum forward current versus heatsink temperature (Rectifier bridge)

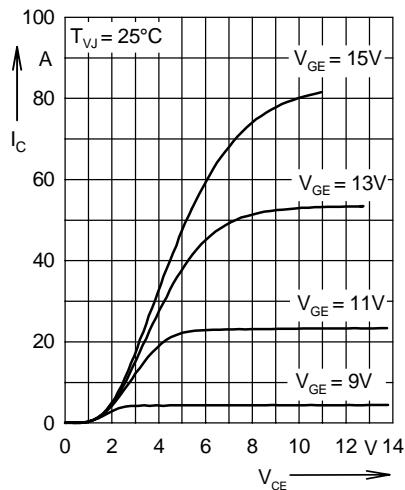


Fig. 6 Output characteristics for braking (IGBT)

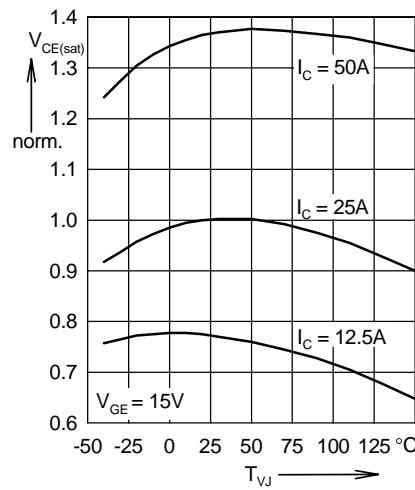


Fig. 7 Saturation voltage versus junction temperature normalized (IGBT)

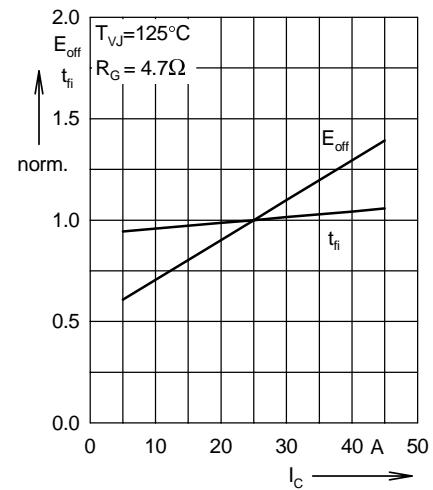


Fig. 8 Turn-off energy per pulse and fall time versus collector current, normalized (IGBT)

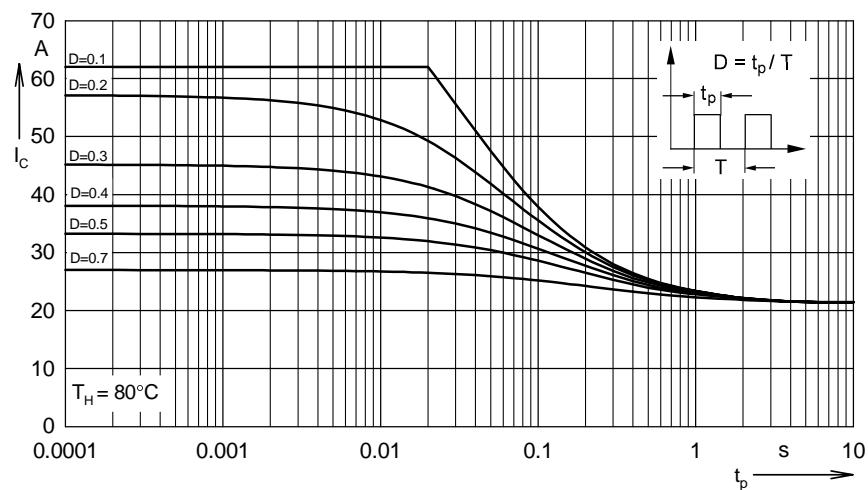


Fig. 9 Collector current versus pulse width and duty cycle (IGBT)

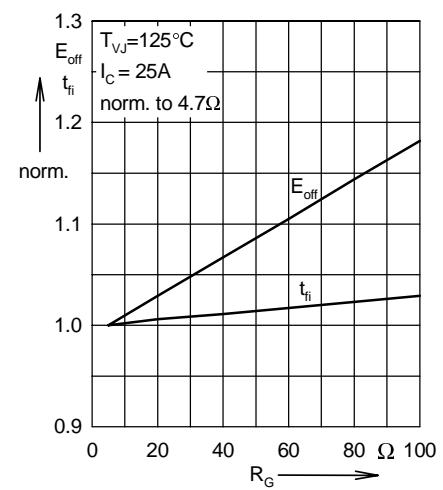


Fig. 10 Turn-off energy per pulse and fall time versus R_G (IGBT)

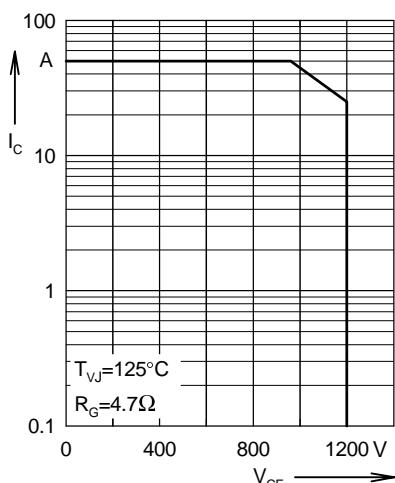


Fig.11 Reverse biased safe operation area (IGBT)

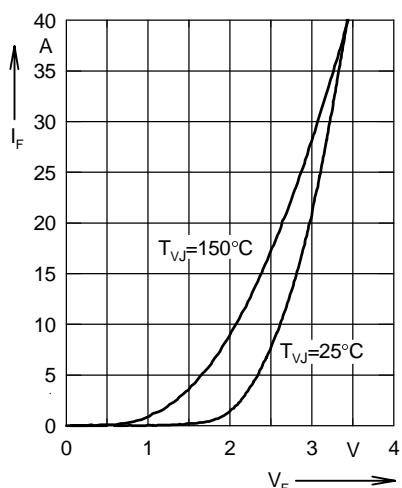


Fig. 12 Forward current versus voltage drop (Fast Diode)

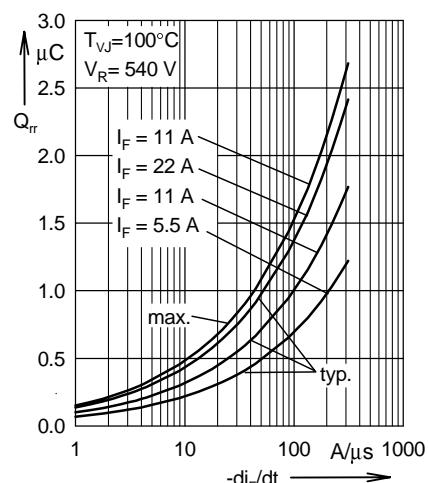


Fig. 13 Recovery charge versus $-di_F/dt$ (Fast Diode)

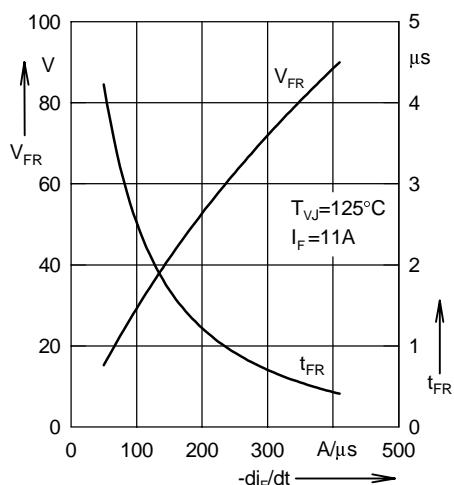


Fig.14 Peak forward voltage and recovery time versus $-di_F/dt$ (Fast Diode)

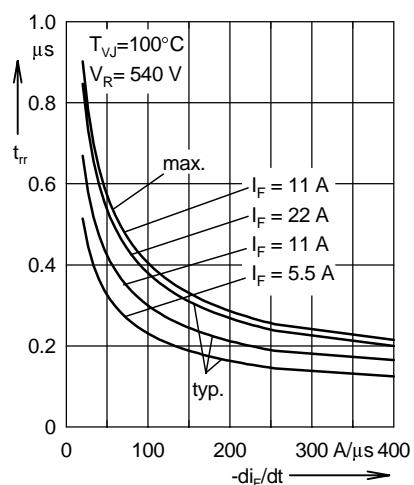


Fig.15 Recovery time versus $-di_F/dt$ (Fast Diode)

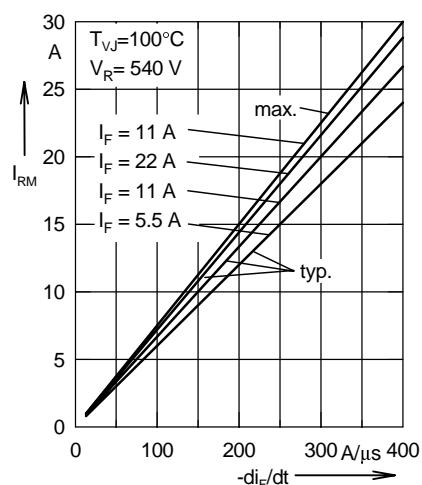


Fig.16 Peak reverse current versus $-di_F/dt$ (Fast Diode)

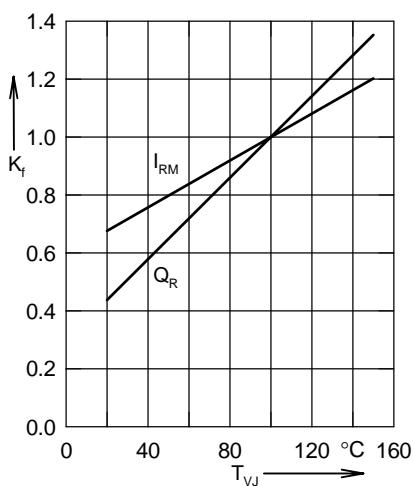


Fig.17 Dynamic parameters versus junction temperature (Fast Diode)

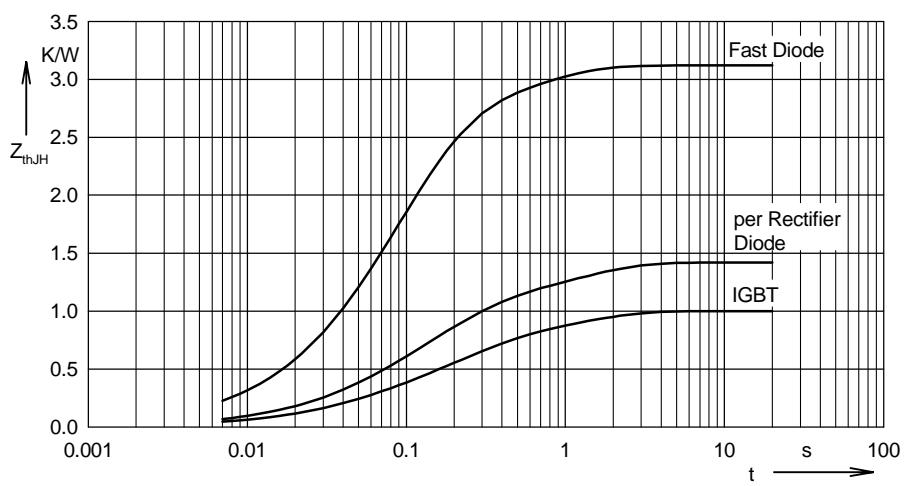


Fig.18 Transient thermal impedance junction to heatsink Z_{thJH}